

QUADRUPLE RS-485 DIFFERENTIAL LINE DRIVERS

 Check for Samples: [SN65LBC174A](#) [SN75LBC174A](#)

FEATURES

- Designed for TIA/EIA-485, TIA/EIA-422 and ISO 8482 Applications
- Signaling Rates ⁽¹⁾ up to 30 Mbps
- Propagation Delay Times < 11 ns
- Low Standby Power Consumption 1.5-mA Max

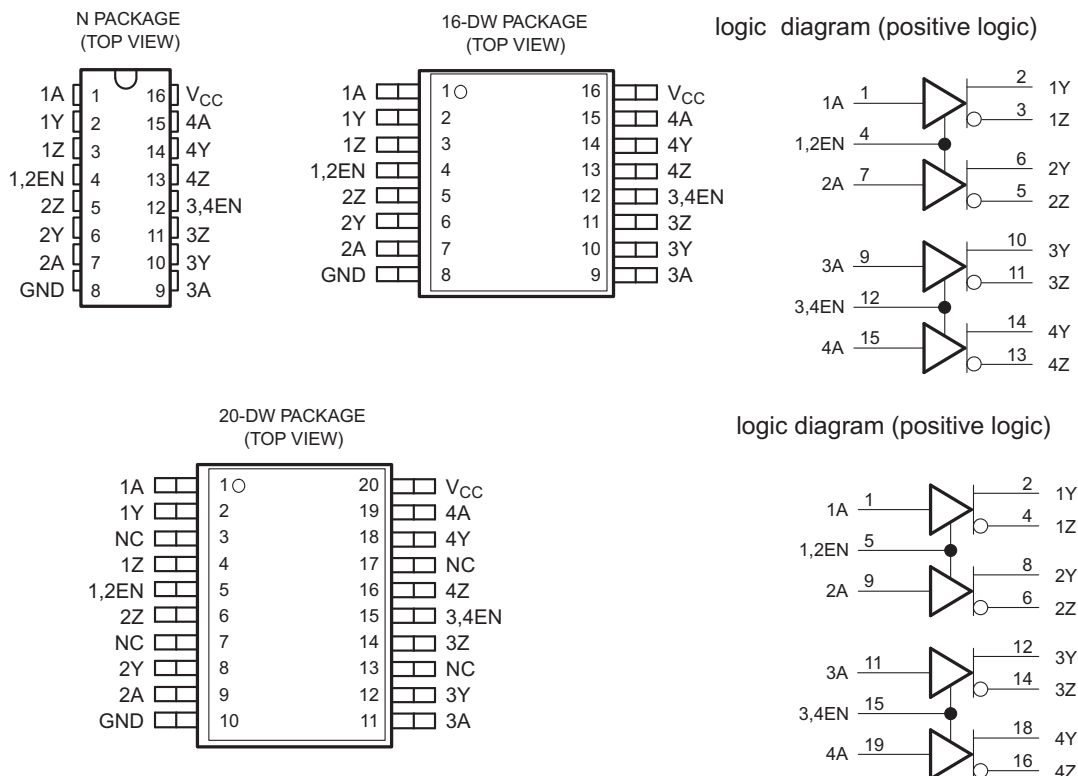
(1) The signaling rate of a line is the number of voltage transitions that are made per second expressed in the units bps (bits per second).

- Output ESD Protection: 12 kV
- Driver Positive- and Negative-Current Limiting
- Power-Up and Power-Down Glitch-Free for Line Insertion Applications
- Thermal Shutdown Protection
- Industry Standard Pin-Out, Compatible With SN75174, MC3487, DS96174, LTC487, and MAX3042

DESCRIPTION

The SN65LBC174A and SN75LBC174A are quadruple differential line drivers with 3-state outputs, designed for TIA/EIA-485 (RS-485), TIA/EIA-422 (RS-422), and ISO 8482 applications.

These devices are optimized for balanced multipoint bus transmission at signaling rates up to 30 million bits per second. The transmission media may be printed-circuit board traces, backplanes, or cables. The ultimate rate and distance of data transfer is dependent upon the attenuation characteristics of the media and the noise coupling to the environment.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

DESCRIPTION (CONTINUED)

Each driver features current limiting and thermal-shutdown circuitry making it suitable for high-speed multipoint applications in noisy environments. These devices are designed using LinBiCMOS®, facilitating low power consumption and robustness.

The two EN inputs provide pair-wise driver enabling, or can be externally tied together to provide enable control of all four drivers with one signal. When disabled or powered off, the driver outputs present a high-impedance to the bus for reduced system loading.

The SN75LBC174A is characterized for operation over the temperature range of 0°C to 70°C. The SN65LBC174A is characterized for operation over the temperature range of –40°C to 85°C.

Table 1. AVAILABLE OPTIONS

T _A	PACKAGE		
	16-PIN PLASTIC SMALL OUTLINE ⁽¹⁾ (JEDEC MS-013)	20-PIN PLASTIC SMALL OUTLINE ⁽¹⁾ (JEDEC MS-013)	16-PIN PLASTIC THROUGH-HOLE (JEDEC MS-001)
0°C to 70°C	SN75LBC174A16DW	SN75LBC174ADW	SN75LBC174AN
	MARKED AS 75LBC174A		
–40°C to 85°C	SN65LBC174A16DW	SN65LBC174DW	SN65LBC174AN
	MARKED AS 65LBC174A		

(1) Add R suffix for taped and reeled version.

Table 2. FUNCTION TABLE (EACH DRIVER)⁽¹⁾

INPUT A	ENABLE EN	OUTPUT Y	OUTPUT Z
L	H	L	H
H	H	H	L
OPEN	H	H	L
L	OPEN	L	H
H	OPEN	H	L
OPEN	OPEN	H	L
X	L	Z	Z

(1) H = high level, L = low level, X = irrelevant, Z = high impedance (off)

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			VALUE / UNIT
Supply voltage range, V_{CC} ⁽²⁾			–0.3 V to 6 V
Voltage range at any bus (DC)			–10 V to 15 V
Voltage range at any bus (transient pulse through 100 Ω , see Figure 8)			–30 V to 30 V
Input voltage range at any A or EN terminal, V_I			–0.5 V to $V_{CC} + 0.5$ V
Electrostatic discharge	Human body model ⁽³⁾	Y, Z, and GND	± 12 kV
		All pins	± 5 kV
	Charged-device model ⁽⁴⁾	All pins	± 1 kV
Storage temperature range, T_{stg}			–65°C to 150°C
Continuous power dissipation			See Dissipation Rating Table

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential I/O bus voltages, are with respect to GND.
- (3) Tested in accordance with JEDEC standard 22, Test Method A114-A.
- (4) Tested in accordance with JEDEC standard 22, Test Method C101.

Table 3. DISSIPATION RATING TABLE

PACKAGE ⁽¹⁾	JEDEC BOARD MODEL	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ⁽²⁾ ABOVE $T_A = 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING
16 DW	LOW K	1200 mW	9.6 mW/°C	769 mW	625 mW
	HIGH K	2240 mW	17.9 mW/°C	1434 mW	1165 mW
20 DW	LOW K	1483 mW	11.86 mW/°C	949 mW	771 mW
	HIGH K	2753 mW	22 mW/°C	1762 mW	1432 mW
16 N	LOW K	1150 mW	9.2 mW/°C	736 mW	598 mW

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.
- (2) This is the inverse of the junction-to-ambient thermal resistance when board-mounted and with no air flow.

RECOMMENDED OPERATING CONDITIONS

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.75	5	5.25	V
Voltage at any bus terminal	Y, Z	–7		12	V
High-level input voltage, V_{IH}	A, EN	2		V_{CC}	V
Low-level input voltage, V_{IL}		0		0.8	
Output current		–60		60	mA
Operating free-air temperature, T_A	SN75LBC174A	0		70	°C
	SN65LBC174A	–40		85	

ELECTRICAL CHARACTERISTICS

over recommended operating conditions

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{IK}	Input clamp voltage	I _I = -18 mA	-1.5	-0.77		V
V _O	Open-circuit output voltage	Y or Z, No load	0		V _{CC}	V
V _{OD(SS)}	Steady-state differential output voltage magnitude ⁽²⁾	No load (open circuit)	3		V _{CC}	V
		R _L = 54 Ω, See Figure 1	1	1.6	2.5	
		With common-mode loading, See Figure 2	1	1.6	2.5	
ΔV _{OD(SS)}	Change in steady-state differential output voltage between logic states	See Figure 1	-0.1		0.1	V
V _{OC(SS)}	Steady-state common-mode output voltage	See Figure 3	2	2.4	2.8	V
ΔV _{OC(SS)}	Change in steady-state common-mode output voltage between logic states	See Figure 3	-0.02		0.02	V
I _I	Input current	A, EN	-50		50	μA
I _{OS}	Short-circuit output current	V _{TEST} = -7 V to 12 V, See Figure 7	-200	V _I = 0 V	200	mA
I _{OZ}	High-impedance-state output current			V _I = V _{CC}		
I _{O(OFF)}	Output current with power off	EN at 0 V	-50		50	μA
I _{CC}	Supply current	V _I = 0 V or V _{CC} , No load		V _{CC} = 0 V	10	mA
				All drivers enabled	23	
C _{IN}	Input Capacitance	A inputs		13		pF
		EN inputs		21		pF

(1) All typical values are at V_{CC} = 5 V and 25°C.

(2) The minimum V_{OD} may not fully comply with TIA/EIA-485-A at operating temperatures below 0°C. System designers should take the possibly lower output signal into account in determining the maximum signal transmission distance.

SWITCHING CHARACTERISTICS

over recommended operating conditions

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PLH}	Propagation delay time, low-to-high level output	5.5	8	11	ns
t _{PHL}	Propagation delay time, high-to-low level output	5.5	8	11	ns
t _r	Differential output voltage rise time	3	7.5	11	ns
t _f	Differential output voltage fall time	3	7.5	11	ns
t _{sk(p)}	Pulse skew t _{PLH} - t _{PHL}		0.6	2	ns
t _{sk(o)}	Output skew ⁽¹⁾		0.6	2	
t _{sk(pp)}	Part-to-part skew ⁽²⁾			2	ns
t _{PZH}	Propagation delay time, high-impedance-to-high-level output			25	ns
t _{PHZ}	Propagation delay time, high-level-output-to-high impedance	See Figure 5		25	ns
t _{PZL}	Propagation delay time, high-impedance-to-low-level output			30	ns
t _{PLZ}	Propagation delay time, low-level-output-to-high impedance	See Figure 6		20	ns

(1) Output skew (t_{sk(o)}) is the magnitude of the time delay difference between the outputs of a single device with all of the inputs connected together.

(2) Part-to-part skew (t_{sk(pp)}) is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate with the same input signals, the same supply voltages, at the same temperature, and have identical packages and test circuits.

PARAMETER MEASUREMENT INFORMATION

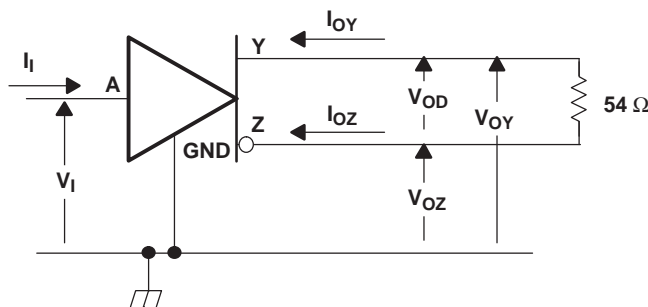


Figure 1. Test Circuit, V_{OD} Without Common-Mode Loading

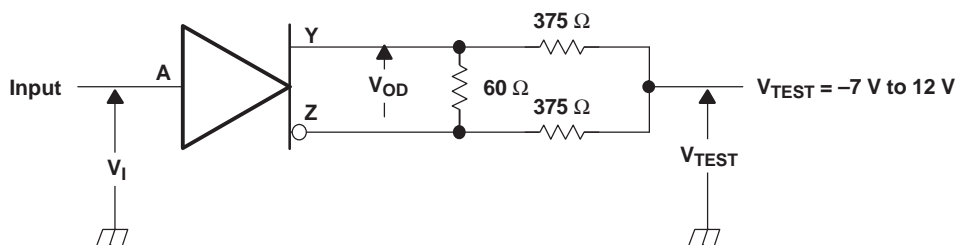
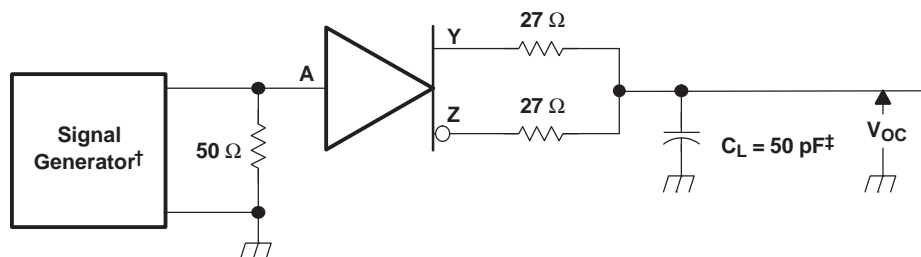


Figure 2. Test Circuit, V_{OD} With Common-Mode Loading

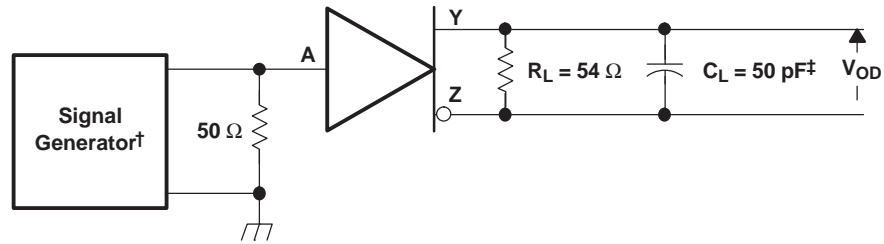


† PRR = 1 MHz, 50% Duty Cycle, $t_r < 6$ ns, $t_f < 6$ ns, $Z_O = 50 \Omega$

‡ Includes probe and jig capacitance

Figure 3. V_{OC} Test Circuit

PARAMETER MEASUREMENT INFORMATION (continued)



† PRR = 1 MHz, 50% Duty Cycle, $t_r < 6$ ns, $t_f < 6$ ns, $Z_O = 50 \Omega$

‡ Includes probe and jig capacitance

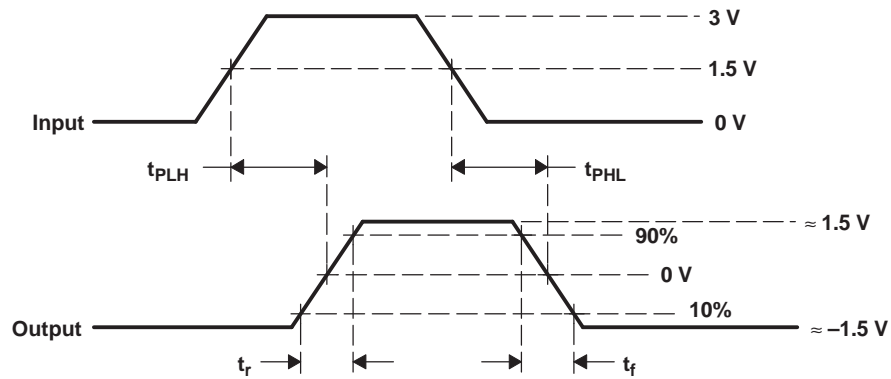
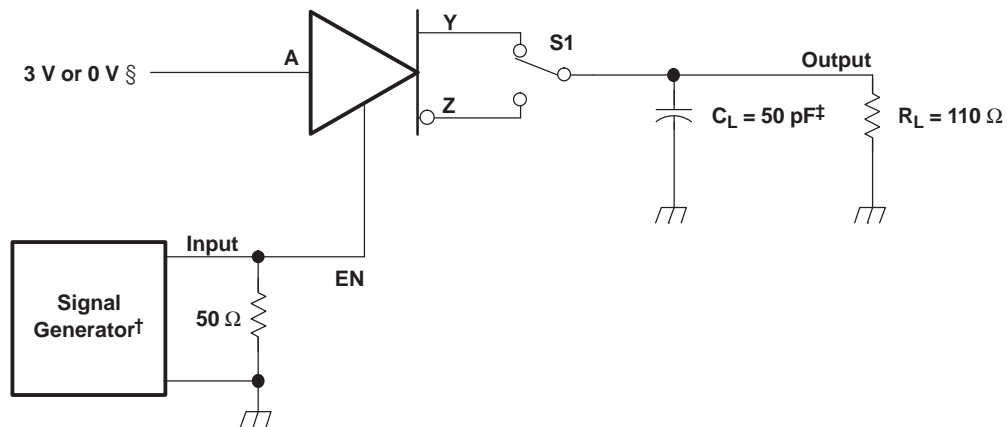


Figure 4. Output Switching Test Circuit and Waveforms

PARAMETER MEASUREMENT INFORMATION (continued)



† PRR = 1 MHz, 50% Duty Cycle, $t_r < 6$ ns, $t_f < 6$ ns, $Z_O = 50 \Omega$

‡ Includes probe and jig capacitance

§ 3 V if testing Y output, 0 V if testing Z output

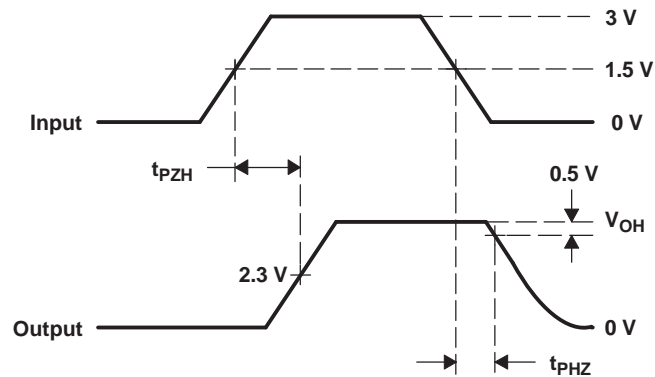
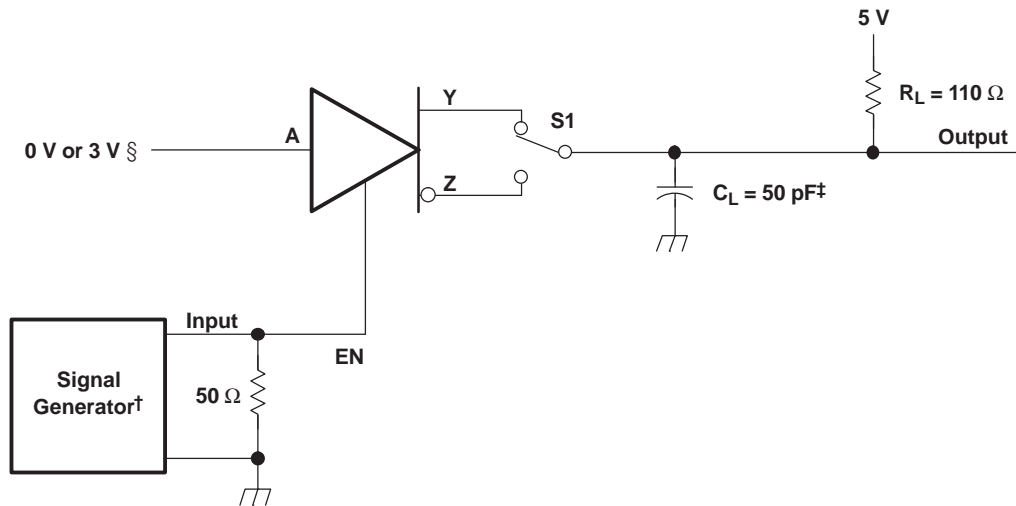


Figure 5. Enable Timing Test Circuit and Waveforms, t_{PZH} and t_{PHZ}

PARAMETER MEASUREMENT INFORMATION (continued)



† PRR = 1 MHz, 50% Duty Cycle, $t_r < 6$ ns, $t_f < 6$ ns, $Z_O = 50 \Omega$

‡ Includes probe and jig capacitance

§ 3 V if testing Y output, 0 V if testing Z output

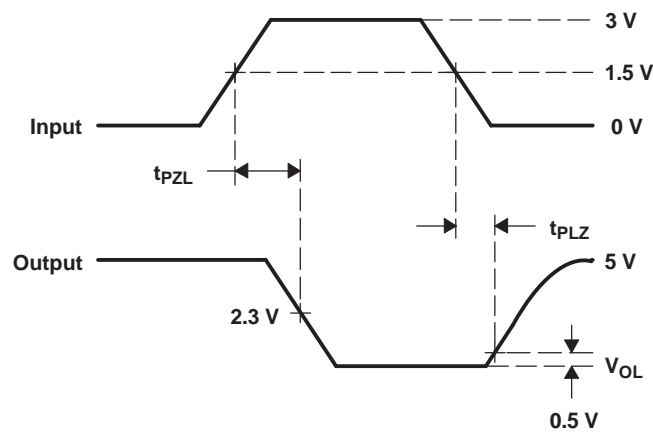


Figure 6. Enable Timing Test Circuit and Waveforms, t_{PZL} and t_{PLZ}

PARAMETER MEASUREMENT INFORMATION (continued)

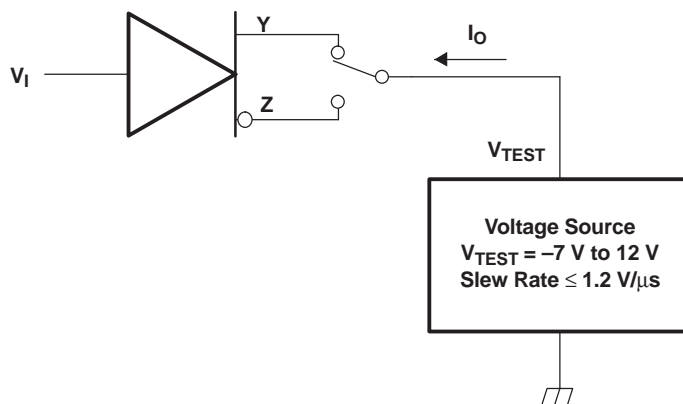


Figure 7. Test Circuit, Short-Circuit Output Current

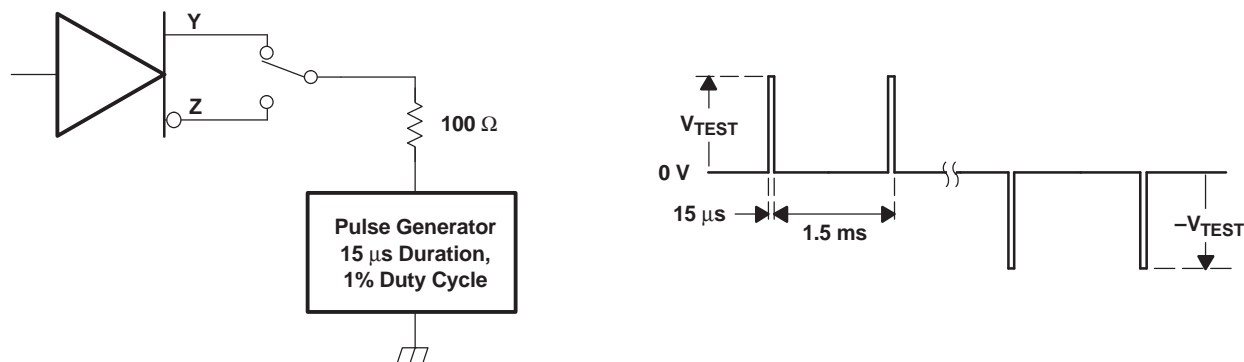
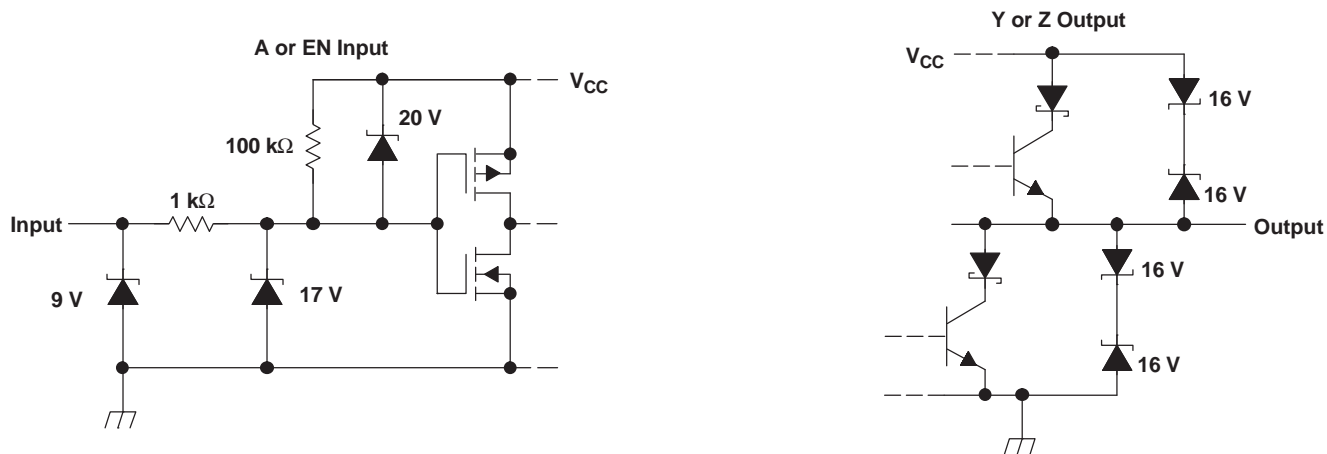


Figure 8. Test Circuit Waveform, Transient Overvoltage Test

EQUIVALENT INPUT AND OUTPUT SCHEMATIC DIAGRAMS



TYPICAL CHARACTERISTICS

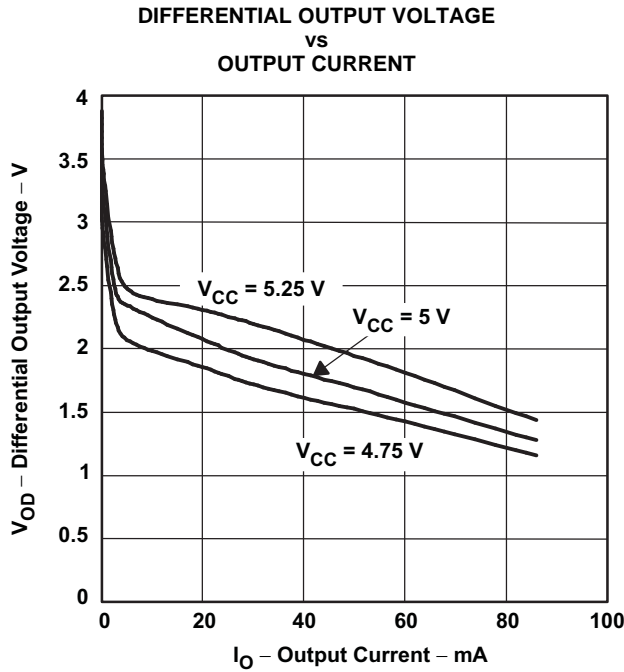


Figure 9.

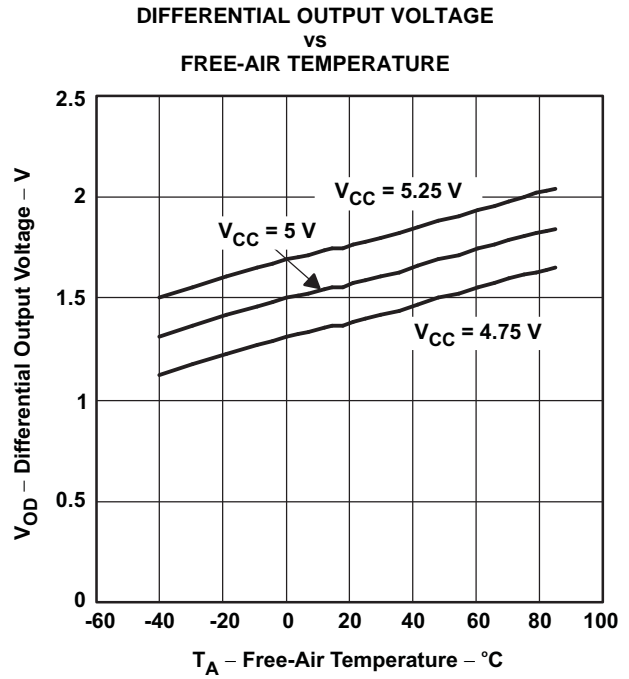


Figure 10.

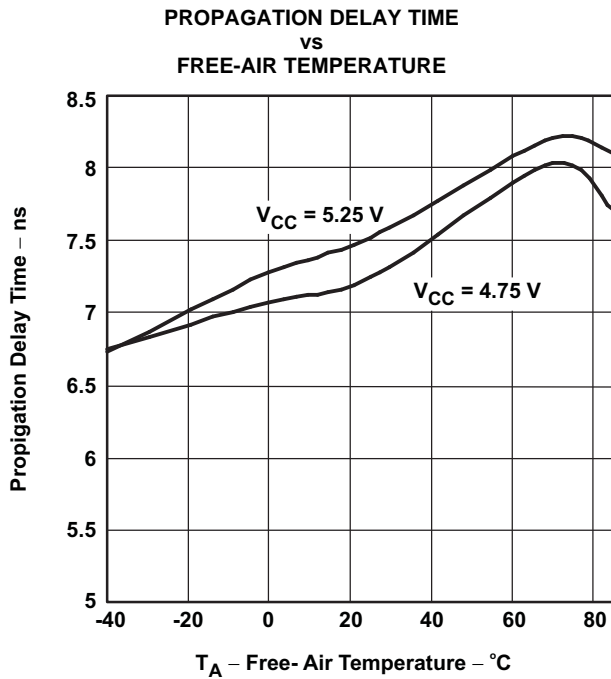


Figure 11.

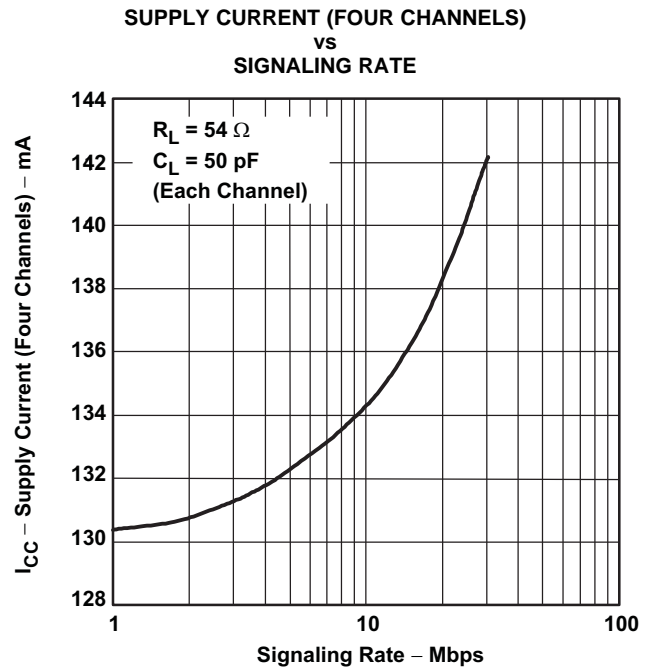


Figure 12.

TYPICAL CHARACTERISTICS (continued)

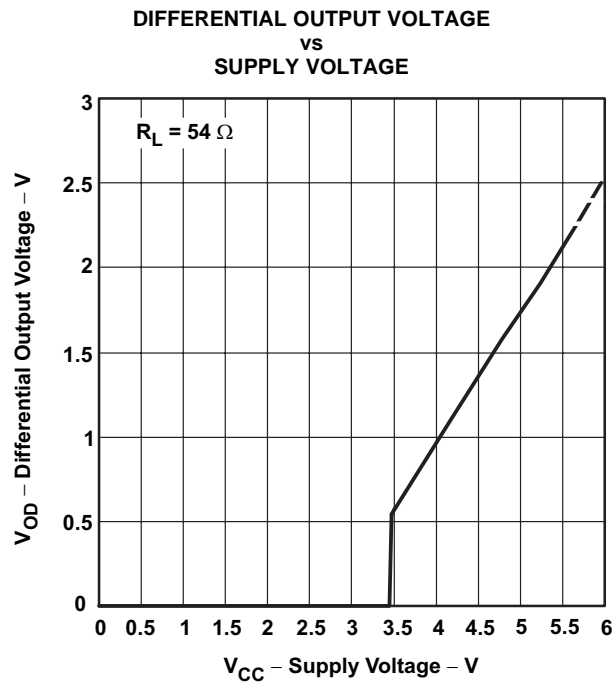


Figure 13.

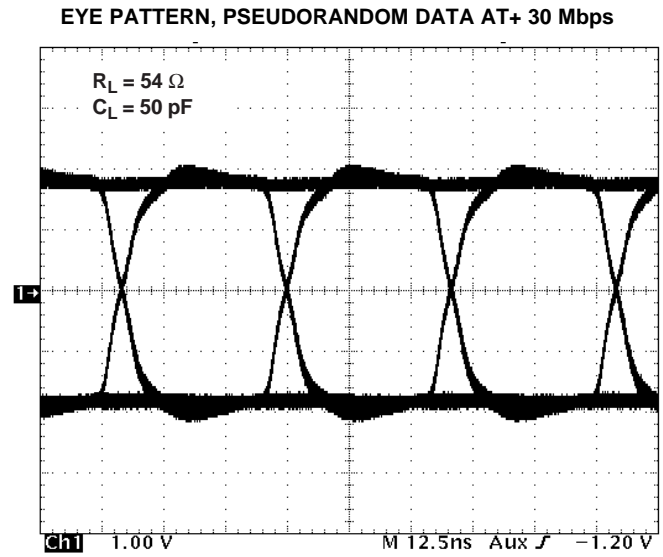


Figure 14.

APPLICATION INFORMATION

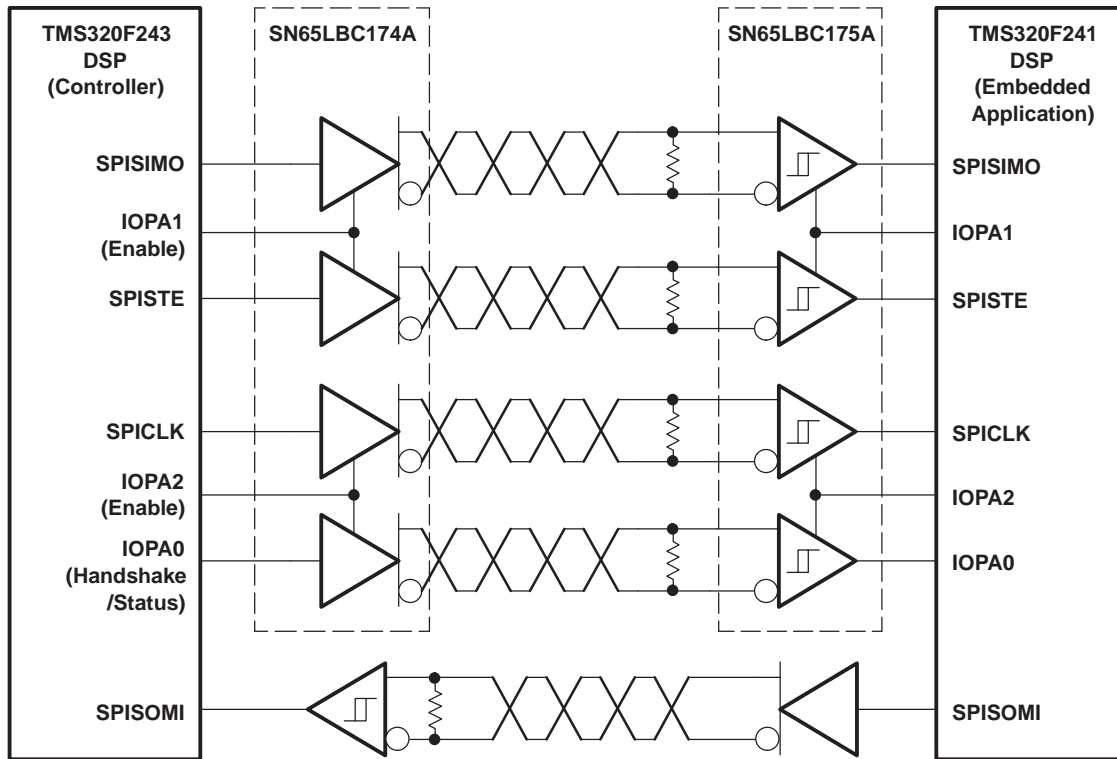


Figure 15. Typical Application Circuit, DSP-to-DSP Link via Serial Peripheral Interface

REVISION HISTORY

Changes from Original (October 2000) to Revision A	Page
<ul style="list-style-type: none"> Changed multiple items through the data sheet. 1 	1
Changes from Revision A (February 2001) to Revision B	Page
<ul style="list-style-type: none"> Changed DW Package appearance 1 Added Figure 13 11 	11
Changes from Revision B (June 2001) to Revision C	Page
<ul style="list-style-type: none"> Changed Features bullet From: Output ESD Protection Exceeds 13 kV To: Output ESD Protection: 11 kV 1 Changed Features bullet for Industry Standard From: Compatible With SN75174, MC3487, and DS96174 To: Compatible With SN75174, MC3487, DS96174, LTC487, and MAX3042 1 	1
Changes from Revision C (May 2003) to Revision D	Page
<ul style="list-style-type: none"> Changed the AVAILABLE OPTIONS table 2 Changed Electrostatic discharge-Human body model-Y, Z, and GND From: 13kV To: 11kV 3 Changed the DISSIPATION RATING TABLE 3 	3

Changes from Revision D (June 2008) to Revision E
Page

- Changed Features bullet From: Output ESD Protection Exceeds 11 kV To: Output ESD Protection: 12 kV 1
 - Changed Electrostatic discharge-Human body model-Y, Z, and GND From: 11kV To: 12kV 3
 - From: A, G, \bar{G} To: A, EN 4
-

Changes from Revision E (July 2008) to Revision F
Page

- Changed FUNCTION TABLE header From: ENABLE G To: ENABLE EN 2
 - Added C_{IN} - Input Capacitance to the Electrical Characteristics table 4
 - Changed the location of the EQUIVALENT INPUT AND OUTPUT SCHEMATIC DIAGRAM 9
-

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN65LBC174A16DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	65LBC174A	Samples
SN65LBC174A16DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	65LBC174A	Samples
SN65LBC174A16DWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	65LBC174A	Samples
SN65LBC174A16DWRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	65LBC174A	Samples
SN65LBC174ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	65LBC174A	Samples
SN65LBC174ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	65LBC174A	Samples
SN65LBC174ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	65LBC174A	Samples
SN65LBC174ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	65LBC174A	Samples
SN65LBC174AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	65LBC174A	Samples
SN75LBC174A16DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75LBC174A	Samples
SN75LBC174A16DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75LBC174A	Samples
SN75LBC174A16DWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75LBC174A	Samples
SN75LBC174ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75LBC174A	Samples
SN75LBC174ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75LBC174A	Samples
SN75LBC174ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75LBC174A	Samples
SN75LBC174ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75LBC174A	Samples
SN75LBC174AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	75LBC174A	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN75LBC174ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	75LBC174A	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN65LBC174A :

- Enhanced Product: [SN65LBC174A-EP](#)

NOTE: Qualified Version Definitions:

- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LBC174A16DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
SN65LBC174ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN75LBC174A16DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
SN75LBC174ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65LBC174A16DWR	SOIC	DW	16	2000	367.0	367.0	38.0
SN65LBC174ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN75LBC174A16DWR	SOIC	DW	16	2000	367.0	367.0	38.0
SN75LBC174ADWR	SOIC	DW	20	2000	367.0	367.0	45.0

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

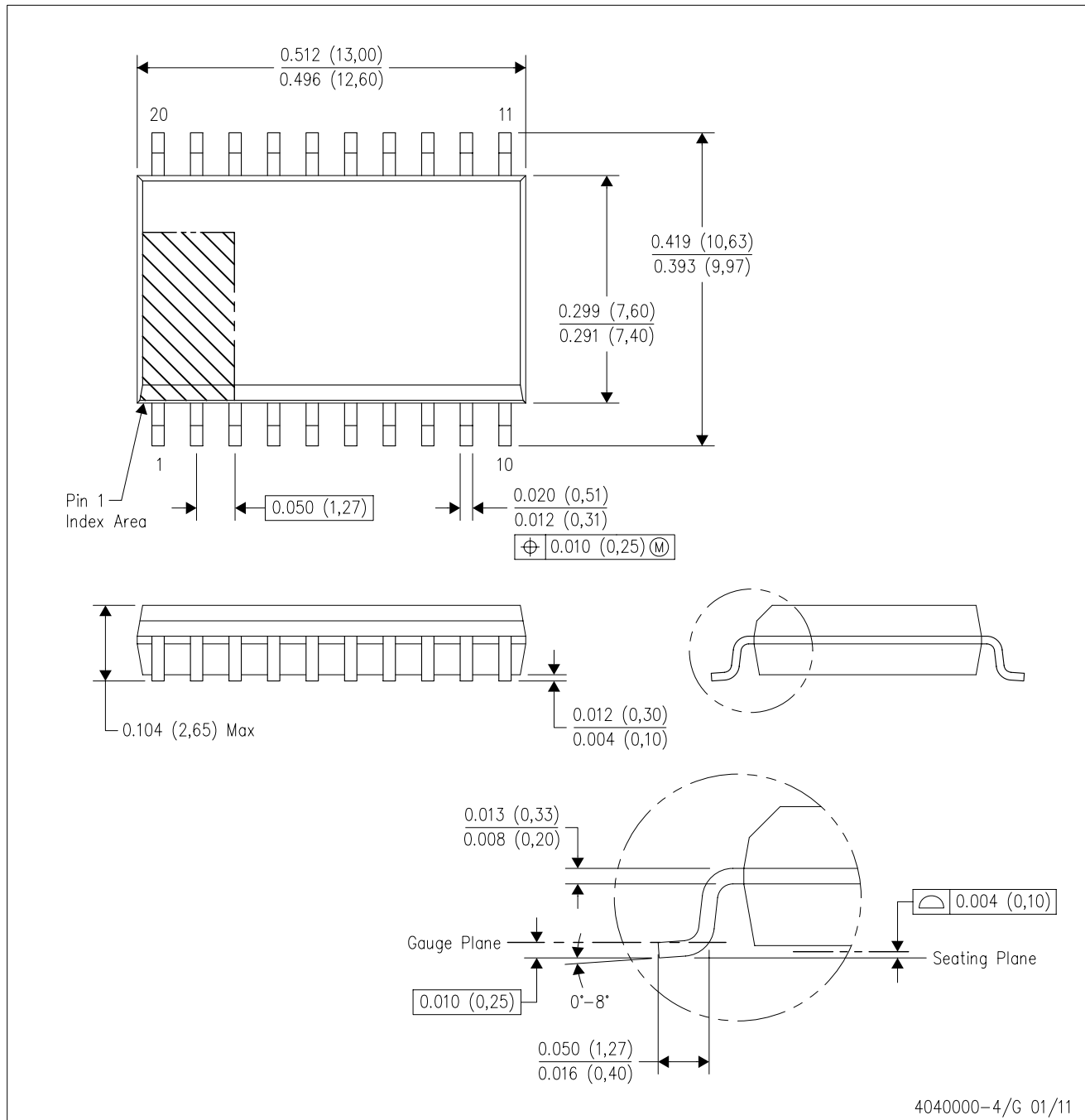
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

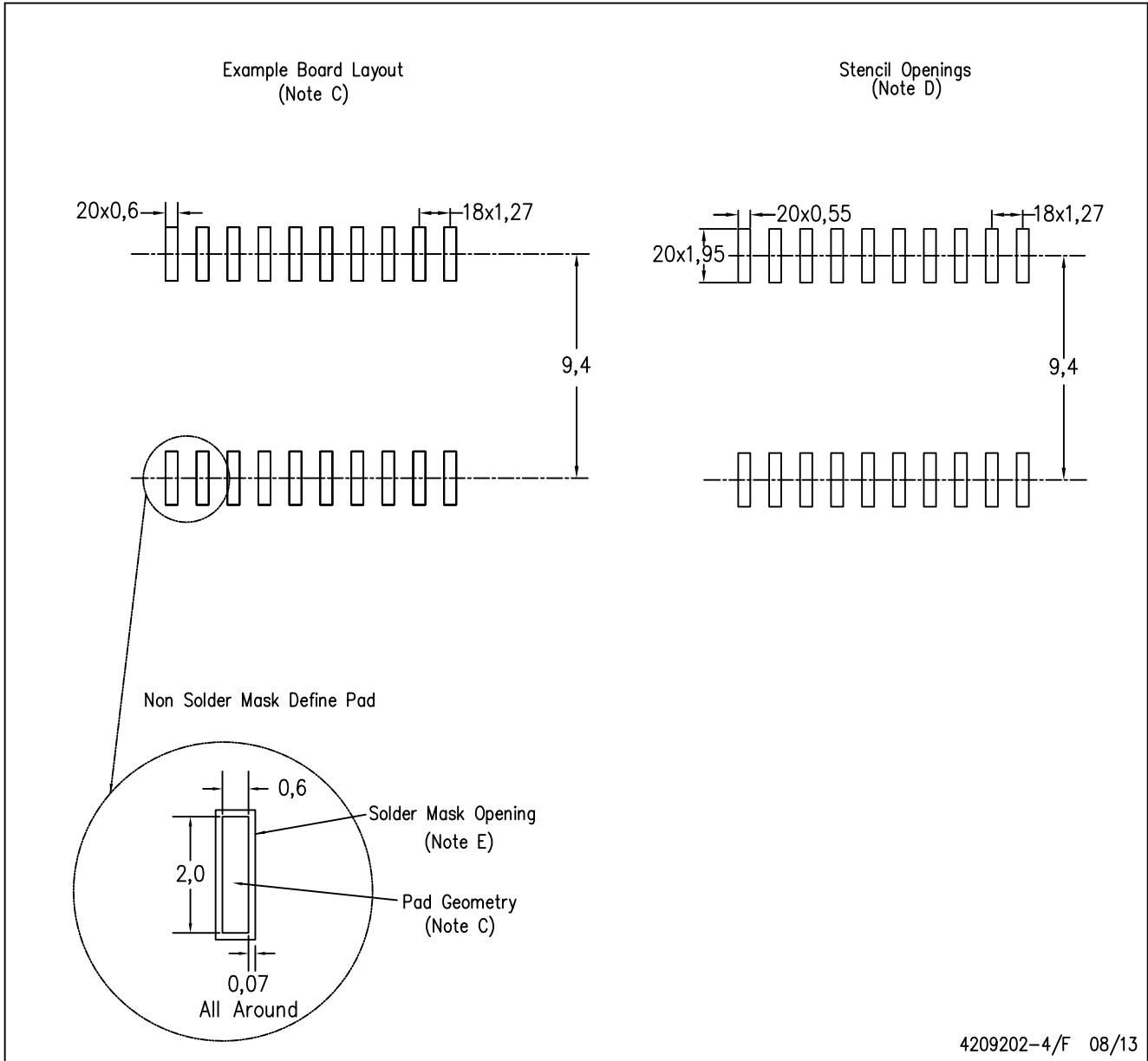
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE

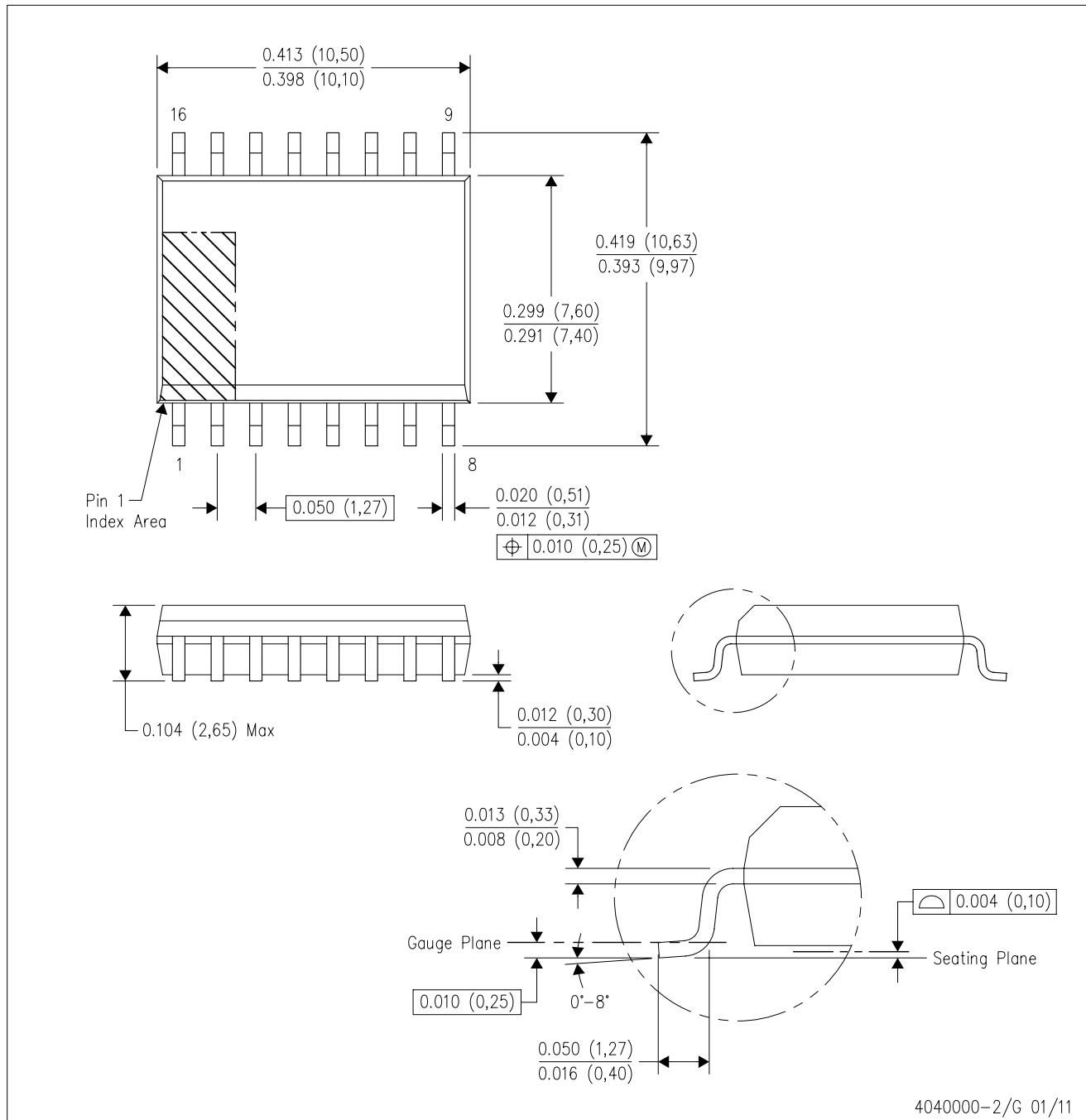


4209202-4/F 08/13

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AA.

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